

## Automotive Process Change Notification

**Date:** September 3, 2014

**PCN Reference:** AU-14-126C, Qualification of Vanguard International Semiconductor Corporation (VIS) for PCube IPS Technology

**Product Reference:** Automotive Intelligent Power Switch (IPS) Products

### To Our Valued Customer:

We thank you for your use of International Rectifier (IR) semiconductor products. Our commitment to customer satisfaction and continuous improvement is demonstrated by our change plans to enhance capacity, quality and reliability. We would like to express our sincere appreciation for your cooperation regarding the following changes, and IR will work closely with you to support your requirements during this transition.

### Type of Change Notification:

- Wafer fab site
- Test site
- Wafer diameter
- Top protective layer material (Gen10.7 MOSFETs only)
- Marking appearance

### Description of Change:

PCube IPS products currently manufactured and wafer-level tested in the IR Newport, South Wales UK (Fab 10) six inch facility will be transferred to the VIS Hsinchu, Taiwan (Fab 2) eight inch wafer fab and subcontractor facilities.

Concurrent with this change, Gen10.7 MOSFETs used in IPS copack products, currently manufactured in the IR Newport, South Wales UK (Fab 10) six inch facility will be transferred to the VIS Hsinchu, Taiwan (Fab 2) facility.

A passivation layer will be added to all VIS Gen10.7 unpassivated MOSFETs in order to improve robustness and reliability.

### Reason for the Change:

As part of a manufacturing consolidation plan announced in 2012, International Rectifier indicated that it would be closing the IR Fab 10 facility and transferring the production capability for certain parts to foundries.

The top marking of the part will be changed to be consistent with standard AU parts.

## Effective Date:

March 3, 2015

## Impact of Change:

No changes to form, fit, or function. The package outline remains the same. Datasheet specifications will not be changed. The location for assembly and final test will not change.

## Products Affected:

IR Part Number	Package	Copack (FET)
AUIPS1031R	DPak	No
AUIPS1031RTRL	DPak	No
AUIPS1031S	D2Pak	No
AUIPS1031STRL	D2Pak	No
AUIPS1041R	Dpak	No
AUIPS1041RTRL	Dpak	No
AUIPS1042GTR	SO8	No
AUIPS1052GTR	SO8	No
AUIPS2031R	DPak	No
AUIPS2031RTRL	DPak	No
AUIPS2041R	DPak	No
AUIPS2041RTRL	DPak	No
AUIPS2052GTR	SO8	No
AUIPS6031R	DPak	No
AUIPS6031RTRL	DPak	No
AUIPS6031S	D2Pak	No
AUIPS6031STRL	D2Pak	No
AUIPS6041GTR	SO8	No
AUIPS6041R	DPak	No
AUIPS6041RTRL	DPak	No
AUIPS6041S	D2Pak	No
AUIPS6041STRL	D2Pak	No
AUIPS7081R	DPak	No
AUIPS7081RTRL	DPak	No
AUIPS7081S	D2Pak	No
AUIPS7081STRL	D2Pak	No
AUIPS7111S	D2Pak	Gen10.7
AUIPS7111STRL	D2Pak	Gen10.7
AUIPS7125R	DPak	No
AUIPS7125RTRL	DPak	No

AUIPS71451GTR	SO8	No
AUIPS7145R	DPak	No
AUIPS7145RTRL	DPak	No
AUIPS72211R	DPak	No
AUIPS72211RTRL	DPak	No
AUIPS7221R	DPak	No
AUIPS7221RTRL	DPak	No
AUIR3200STR	SO8	No
AUIR3240STR	SO8	No
AUIR3313S	D2Pak	Gen7
AUIR3313STRL	D2Pak	Gen7
AUIR3314S	D2Pak	Gen7
AUIR3314STRL	D2Pak	Gen7
AUIR3315S	D2Pak	Gen7
AUIR3315STRL	D2Pak	Gen7
AUIR3317S	D2Pak	Gen7
AUIR3317STRL	D2Pak	Gen7
AUIR3330S	D2Pak	Gen10.7
AUIR3330STRL	D2Pak	Gen10.7
IPS7071GTRPBF	SO8	No

### Method of Identifying Changed Product:

Wafer fab origins will not be distinguished through the external part making or shipping labels; however, IR internal systems will be able to trace the site of the wafer lots used to produce the final product.

### Qualification and Supporting Data Availability:

Contact your IR representative.

### Sample Availability:

Contact your IR representative.

### Contact Information:

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